

TOSHIBA Photocoupler GaAs Ired & Photo-Transistor

TLP284

Programmable Controllers
 AC/DC-Input Module
 Hybrid ICs

TLP284 consist of photo transistor, optically coupled to two gallium arsenide infrared emitting diode connected inverse parallel, and can operate directly by AC input current

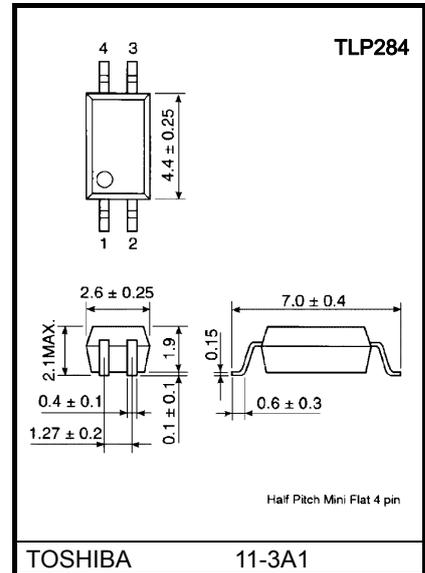
Since TLP284 are guaranteed wide operating temperature (Ta=-55 to 110 °C) and high isolation voltage (3750Vrms), it's suitable for high-density surface mounting applications such as programmable controllers and hybrid ICs.

- Collector-emitter voltage : 80 V (min)
- Current transfer ratio : 50% (min)
 Rank GB :100% (min)
- Isolation voltage : 3750 Vrms (min)
- Guaranteed performance over -55 to 110 °C
- UL Recognized : UL1577 , File No. E67349
- cUL Recognized : CSA Component Acceptance Service No.5A
- BSI (under application) : BS EN 60065: 2002,
 : BS EN 60950-1: 2006
- Option (V4)
 VDE approved : EN60747-5-2
 Maximum operating insulation voltage : 707 Vpk
 Highest permissible over voltage : 6000 Vpk
 **(Note) When a EN60747-5-2 approved type is needed,
 please designate the "Option(V4)"**

Construction Mechanical Rating

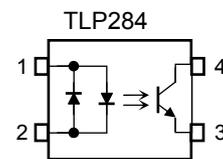
| | |
|----------------------|--------------|
| Creepage Distance | 5.0 mm (min) |
| Clearance | 5.0 mm (min) |
| Insulation Thickness | 0.4 mm (min) |

Unit in mm



Weight: 0.05 g (typ.)

Pin Configuration



- 1 : Anode
 Cathode
- 2 : Cathode
 Anode
- 3 : Emitter
- 4 : Collector

Current Transfer Ratio

| TYPE | Classi- Fication(Note1) | Current Transfer Ratio (%) (I _C / I _F) | | Marking of Classification |
|--------|----------------------------|---|-----|---------------------------|
| | | I _F = 5 mA, V _{CE} = 5 V, T _a = 25°C | | |
| | | Min | Max | |
| TLP284 | Blank | 50 | 600 | Blank , YE,GR,BL,GB |
| | Rank Y | 50 | 150 | YE |
| | Rank GR | 100 | 300 | GR |
| | Rank BL | 200 | 600 | BL |
| | Rank GB | 100 | 600 | GB |

Note1: Ex. rank GB: TLP284 (GB)

Application type name for certification test, please use standard product type name, i.e.

TLP284 (GB): TLP284

Absolute Maximum Ratings (T_a = 25°C)

| Characteristic | | Symbol | Rating | Unit |
|---|---|---------------------|------------------------------|------------------|
| LED | Forward current | I _{F(RMS)} | ±50 | mA |
| | Forward current derating | ΔI _F /°C | -1.0 (T _a ≥ 75°C) | mA /°C |
| | Pulse forward current (Note2) | I _{FP} | ±1 | A |
| | Junction temperature | T _j | 125 | °C |
| Detector | Collector-emitter voltage | V _{CEO} | 80 | V |
| | Emitter-collector voltage | V _{ECO} | 7 | V |
| | Collector current | I _C | 50 | mA |
| | Collector power dissipation (1 circuit) | P _C | 150 | mW |
| | Collector power dissipation derating (T _a ≥ 25°C) | ΔP _C /°C | -1.5 | mW /°C |
| | Junction temperature | T _j | 125 | °C |
| Storage temperature range | | T _{stg} | -55~125 | °C |
| Operating temperature range | | T _{opr} | -55~110 | °C |
| Lead soldering temperature | | T _{sol} | 260 (10s) | °C |
| Total package power dissipation | | P _T | 200 | mW |
| Total package power dissipation derating (T _a ≥ 25°C) | | ΔP _T /°C | -2.0 | mW /°C |
| Isolation voltage (Note3) | | BV _S | 3750 | V _{rms} |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note2: Pulse width ≤ 100μs, frequency 100Hz

Note3: AC, 1min., R.H.≤ 60%, Device considered a two terminal device: LED side pins shorted together and detector side pins shorted together.

Individual Electrical Characteristics (Ta = 25°C)

| Characteristic | | Symbol | Test Condition | Min | Typ | Max | Unit |
|---------------------------------------|-------------------------------------|----------------------------|--|-----|-------------|-------------|---------------|
| LED | Forward voltage | V_F | $I_F = \pm 10 \text{ mA}$ | 1.0 | 1.15 | 1.3 | V |
| | Capacitance | C_T | $V = 0, f = 1 \text{ MHz}$ | — | 60 | — | pF |
| Detector | Collector-emitter breakdown voltage | $V_{(BR)CEO}$ | $I_C = 0.5 \text{ mA}$ | 80 | — | — | V |
| | Emitter-collector breakdown voltage | $V_{(BR)ECO}$ | $I_E = 0.1 \text{ mA}$ | 7 | — | — | V |
| | Collector dark current (Note 5) | I_{CEO} | $V_{CE} = 48 \text{ V}$, Ambient light below (100 lx) (Note 4) | — | 0.01 (2) | 0.1 (10) | μA |
| | | | $V_{CE} = 48 \text{ V}$, $T_a = 85^\circ\text{C}$ Ambient light below (100 lx) (Note 4) | — | 2 (4) | 50 (50) | μA |
| Capacitance (collector to emitter) | C_{CE} | $V = 0, f = 1 \text{ MHz}$ | — | 10 | — | pF | |

Note 4: Irradiation to marking side using standard light bulb.

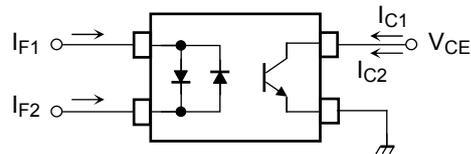
Note 5: Because of the construction, leak current might be increased by ambient light. Please use photocoupler with less ambient light.

Coupled Electrical Characteristics (Ta = 25°C)

| Characteristic | Symbol | Test Condition | Min | Typ. | Max | Unit |
|--------------------------------------|--------------------------|--|------|------|-----|---------------|
| Current transfer ratio | I_C / I_F | $I_F = \pm 5 \text{ mA}, V_{CE} = 5 \text{ V}$ Rank GB | 50 | — | 600 | % |
| | | | 100 | — | 600 | |
| Saturated CTR | $I_C / I_F (\text{sat})$ | $I_F = \pm 1 \text{ mA}, V_{CE} = 0.4 \text{ V}$ Rank GB | — | 60 | — | % |
| | | | 30 | — | — | |
| Collector-emitter saturation voltage | $V_{CE} (\text{sat})$ | $I_C = 2.4 \text{ mA}, I_F = \pm 8 \text{ mA}$ | — | — | 0.4 | V |
| | | $I_C = 0.2 \text{ mA}, I_F = \pm 1 \text{ mA}$ Rank GB | — | 0.2 | — | |
| | | | — | — | 0.4 | |
| Off-state collector current | $I_{C(\text{off})}$ | $V_F = \pm 0.7 \text{ V}, V_{CE} = 48 \text{ V}$ | — | — | 10 | μA |
| CTR symmetry | $I_C (\text{ratio})$ | $I_C (I_F = -5 \text{ mA}) / I_C (I_F = 5 \text{ mA})$ Note 6 | 0.33 | — | 3 | — |

Note 6:

$$I_C(\text{ratio}) = \frac{I_{C2}(I_F = I_{F2}, V_{CE} = 5\text{V})}{I_{C1}(I_F = I_{F1}, V_{CE} = 5\text{V})}$$



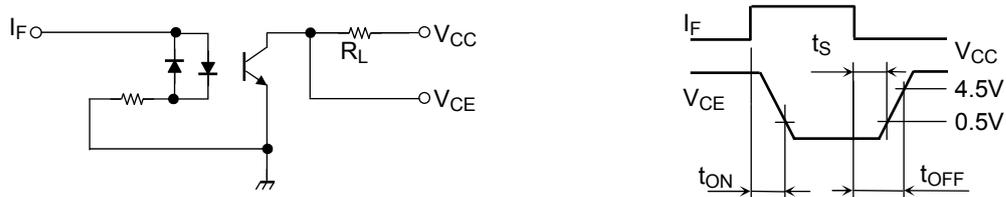
Isolation Characteristics (Ta = 25°C)

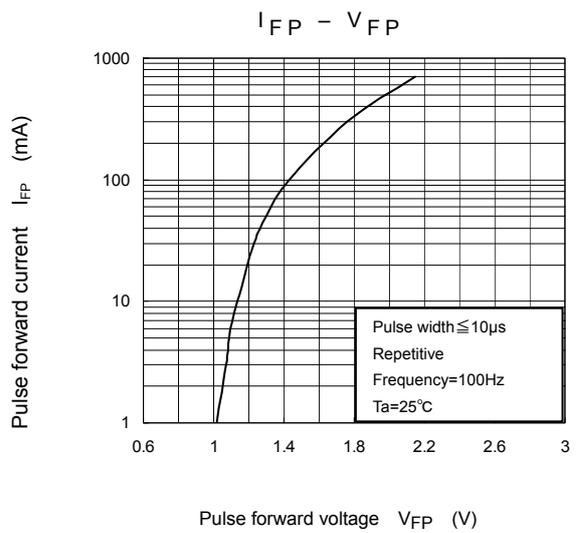
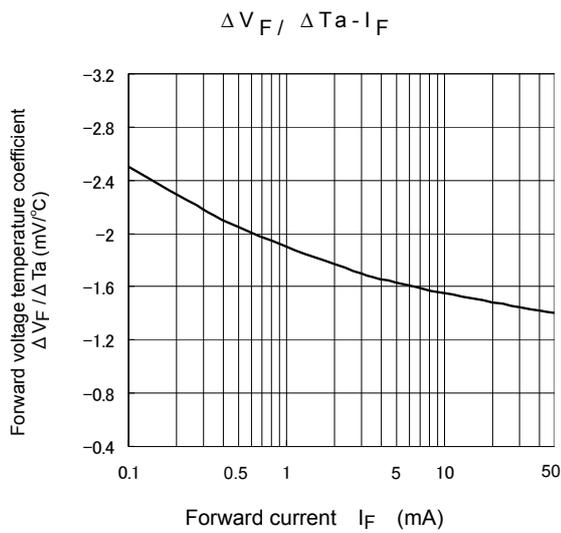
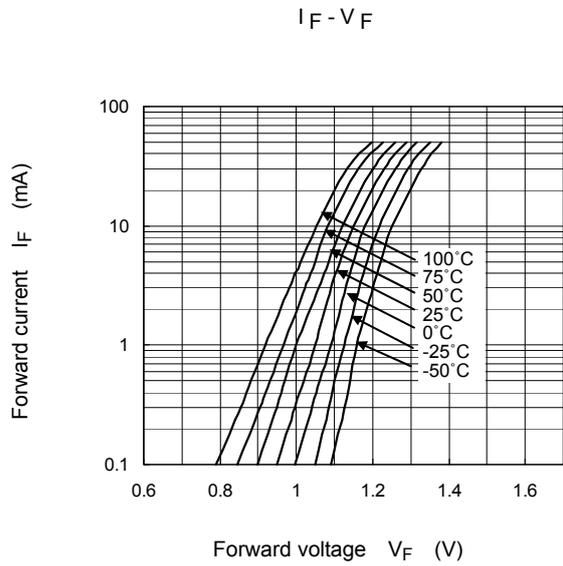
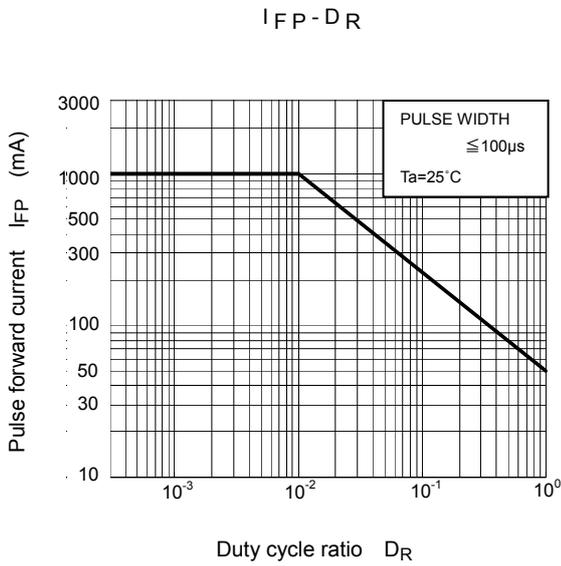
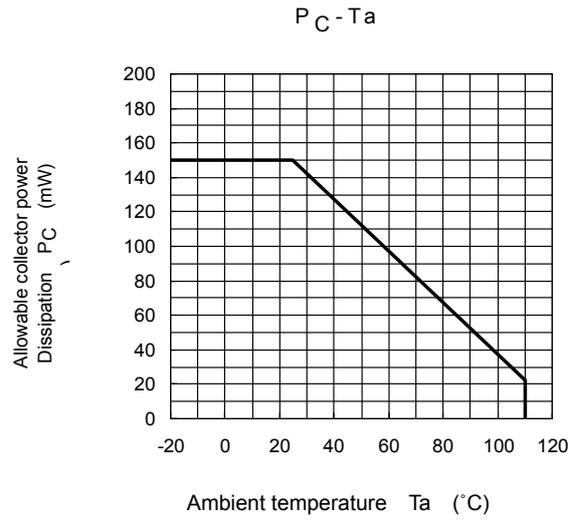
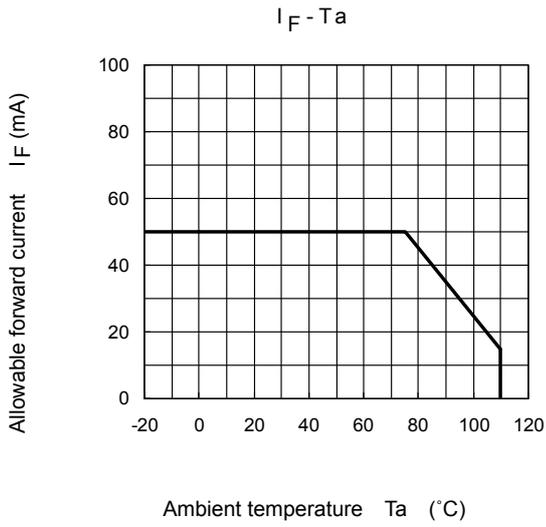
| Characteristic | Symbol | Test Condition | Min | Typ. | Max | Unit |
|-----------------------------|-----------------|------------------------------------|--------------------|------------------|-----|------------------|
| Capacitance input to output | C _S | V _S = 0V, f = 1 MHz | — | 0.8 | — | pF |
| Isolation resistance | R _S | V _S = 500 V, R.H. ≤ 60% | 1×10 ¹² | 10 ¹⁴ | — | Ω |
| Isolation voltage | BV _S | AC, 1 minute | 3750 | — | — | V _{rms} |
| | | AC, 1 second, in oil | — | 10000 | — | |
| | | DC, 1 minute, in oil | — | 10000 | — | V _{dc} |

Switching Characteristics (Ta = 25°C)

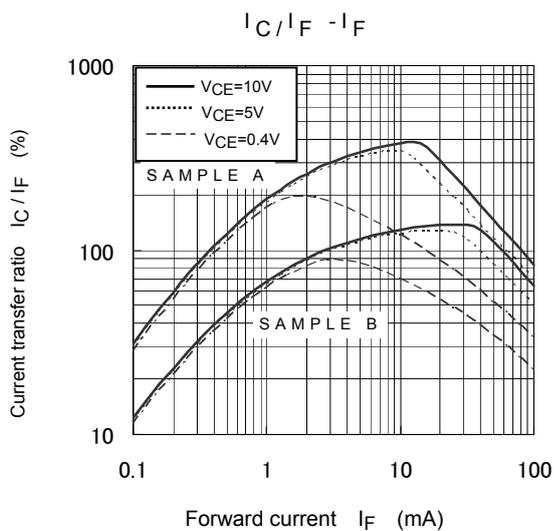
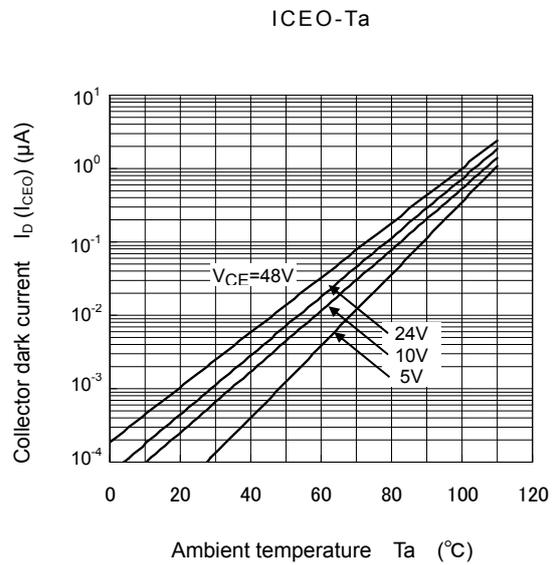
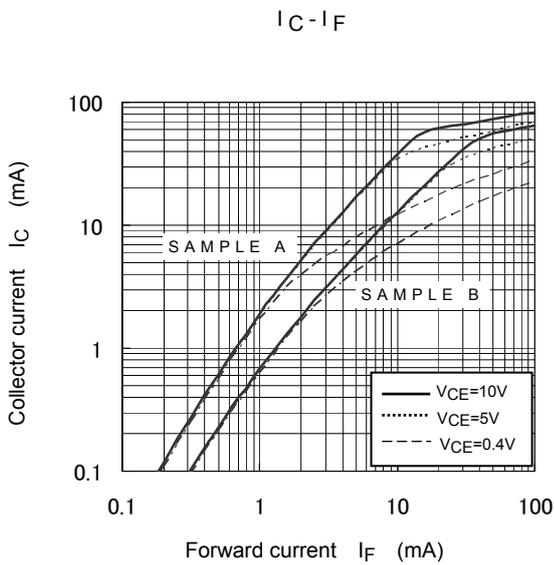
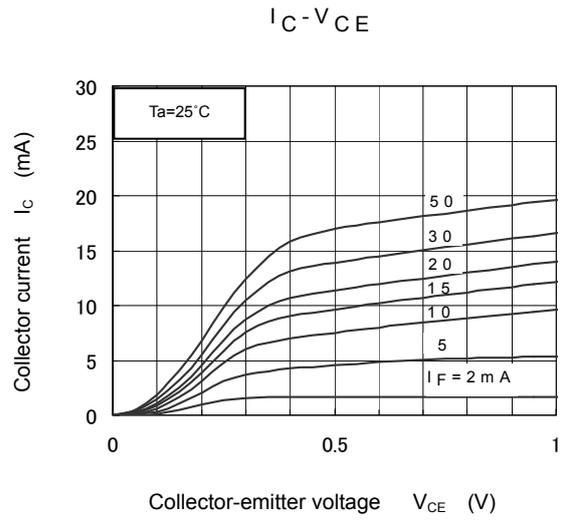
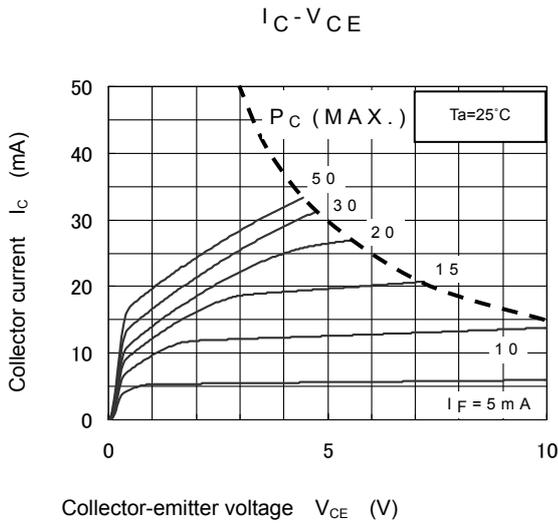
| Characteristic | Symbol | Test Condition | Min | Typ. | Max | Unit |
|----------------|------------------|---|-----|------|-----|------|
| Rise time | t _r | V _{CC} = 10 V, I _C = 2 mA R _L = 100 Ω | — | 2 | — | μs |
| Fall time | t _f | | — | 3 | — | |
| Turn-on time | t _{on} | | — | 3 | — | |
| Turn-off time | t _{off} | | — | 3 | — | |
| Turn-on time | t _{ON} | R _L = 1.9 kΩ V _{CC} = 5 V, I _F = ±16 mA (Fig.1) | — | 2 | — | μs |
| Storage time | t _s | | — | 25 | — | |
| Turn-off time | t _{OFF} | | — | 40 | — | |

(Fig. 1): Switching time test circuit

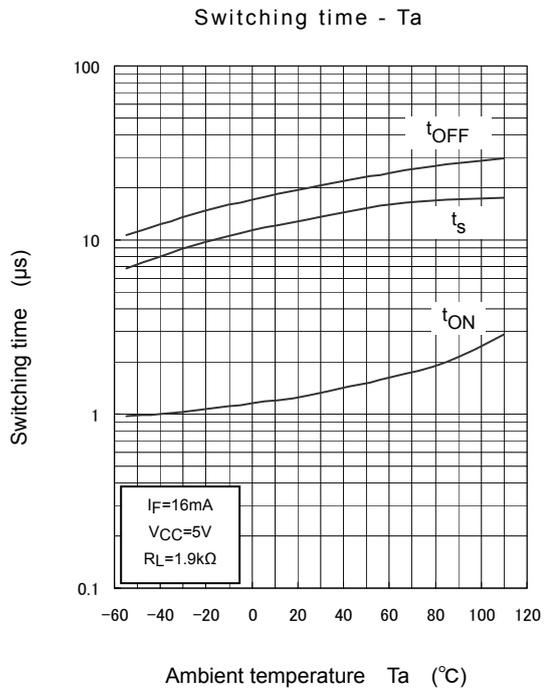
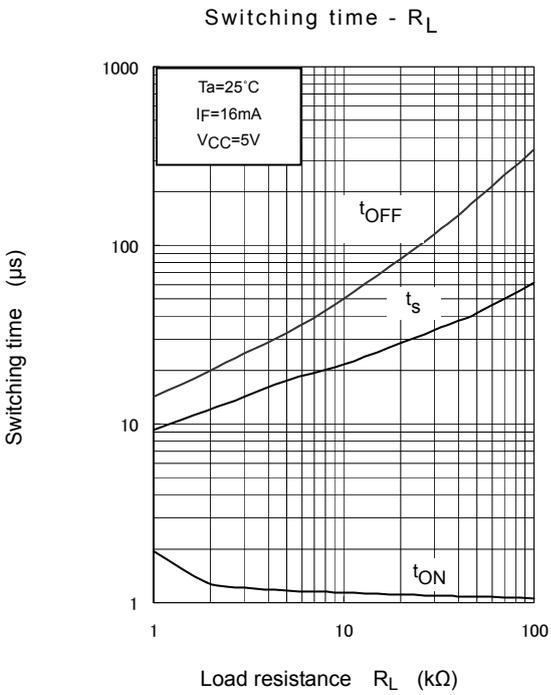
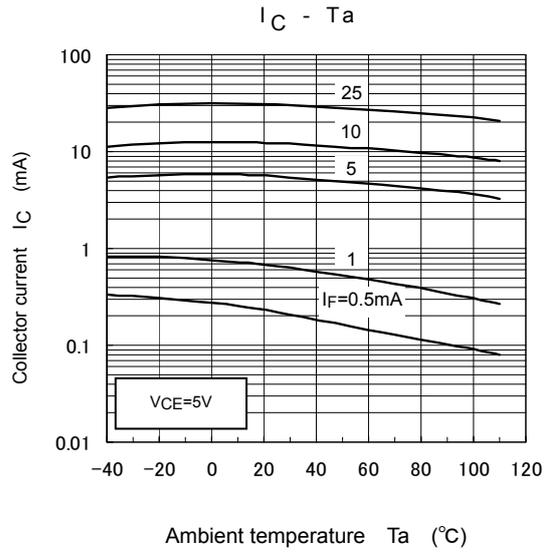
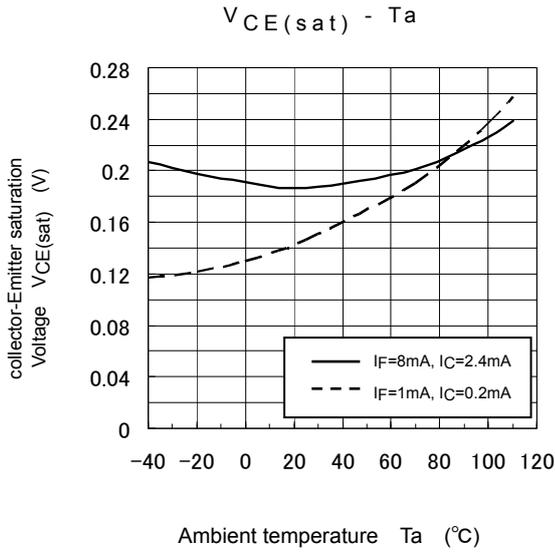




*The above graphs show typical characteristic.



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Soldering and Storage

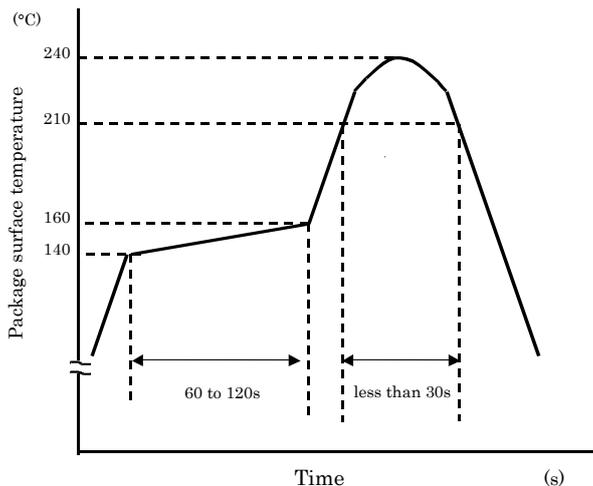
1. Soldering

1.1 Soldering

When using a soldering iron or medium infrared ray/hot air reflow, avoid a rise in device temperature as much as possible by observing the following conditions.

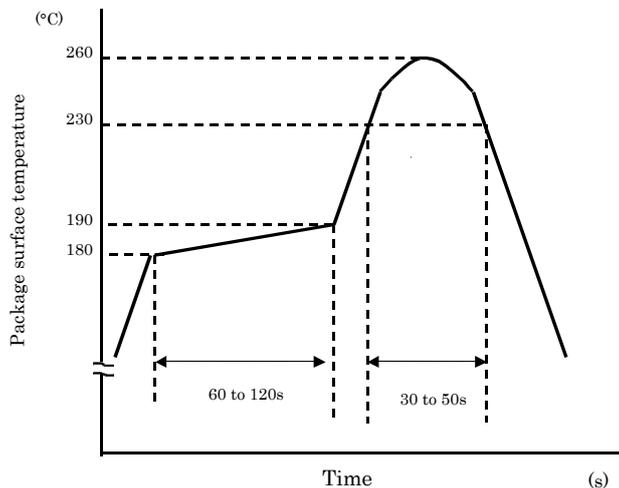
1) Using solder reflow

· Temperature profile example of lead (Pb) solder



This profile is based on the device's maximum heat resistance guaranteed value. Set the preheat temperature/heating temperature to the optimum temperature corresponding to the solder paste type used by the customer within the described profile.

· Temperature profile example of using lead (Pb)-free solder



This profile is based on the device's maximum heat resistance guaranteed value. Set the preheat temperature/heating temperature to the optimum temperature corresponding to the solder paste type used by the customer within the described profile.

2) Using solder flow (for lead (Pb) solder, or lead (Pb)-free solder)

- Please preheat it at 150°C between 60 and 120 seconds.
- Complete soldering within 10 seconds below 260°C. Each pin may be heated at most once.

3) Using a soldering iron

Complete soldering within 10 seconds below 260°C, or within 3 seconds at 350°C. Each pin may be heated at most once.

2. Storage

- 1) Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- 2) Follow the precautions printed on the packing label of the device for transportation and storage.
- 3) Keep the storage location temperature and humidity within a range of 5°C to 35°C and 45% to 75%, respectively.
- 4) Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- 5) Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- 6) When restoring devices after removal from their packing, use anti-static containers.
- 7) Do not allow loads to be applied directly to devices while they are in storage.
- 8) If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.

Option: Specification for Embossed-Tape Packing (TP) for Mini-Flat Coupler

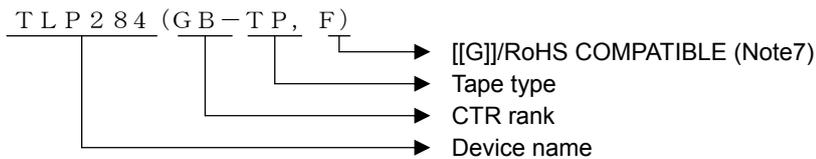
1. Applicable Package

| | |
|---------|-------------------|
| Package | Product Type |
| SOP4 | Mini-Flat Coupler |

2. Product Naming System

Type of package used for shipment is denoted by a symbol suffix after a product number. The method of classification is as below.

(Example)



3. Tape Dimensions

3.1 Orientation of Device in Relation to Direction of Tape Movement

Device orientation in the recesses is as shown in Figure 1.

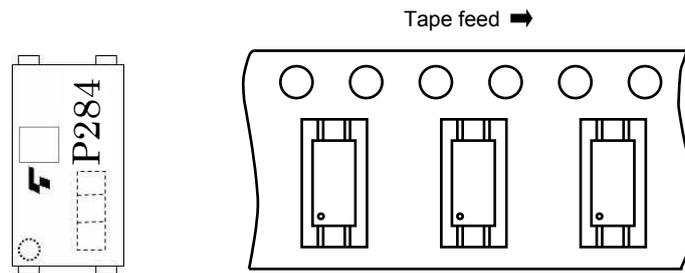


Figure 1 Device Orientation

3.2 Tape Packing Quantity : 2500 devices per reel

3.3 Empty Device Recesses Are as Shown in Table 1.

Table 1 Empty Device Recesses

| | Standard | Remarks |
|---|-------------------------|--|
| Occurrences of 2 or more successive empty device recesses | 0 | Within any given 40-mm section of tape, not including leader and trailer |
| Single empty device recesses | 6 device (max) per reel | Not including leader and trailer |

3.4 Start and End of Tape

The start of the tape has 50 or more empty holes. The end of tape has 50 or more empty holes and two empty turns only for a cover tape.

3.5 Tape Specification

- (1) Tape material: Plastic (protection against electrostatics)
- (2) Dimensions: The tape dimensions are as shown in Figure 2 and table 2.

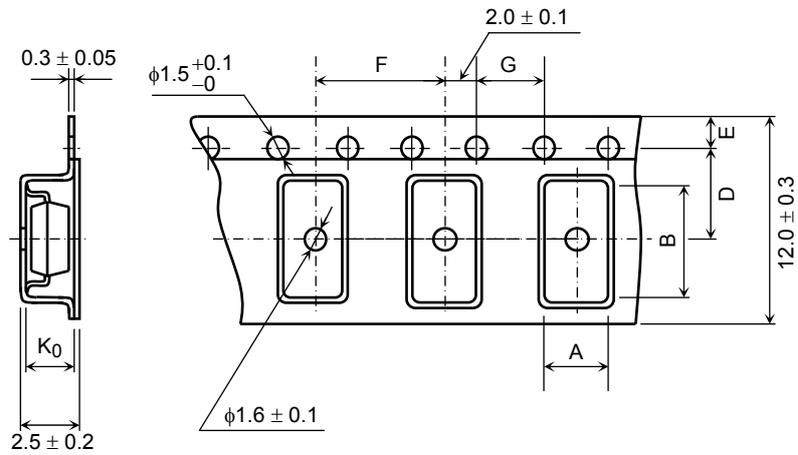


Figure 2 Tape Forms

Table 2 Tape Dimensions

Unit: mm
Unless otherwise specified: ±0.1

| Symbol | Dimension | Remark |
|----------------|-----------|---|
| A | 3.1 | — |
| B | 7.5 | — |
| D | 5.5 | Center line of indented square hole and sprocket hole |
| E | 1.75 | Distance between tape edge and hole center |
| F | 8.0 | Cumulative error $\begin{matrix} +0.1 \\ -0.3 \end{matrix}$ (max) per 10 feed holes |
| G | 4.0 | Cumulative error $\begin{matrix} +0.1 \\ -0.3 \end{matrix}$ (max) per 10 feed holes |
| K ₀ | 2.3 | Internal space |

3.6 Reel

- (1) Material: Plastic
- (2) Dimensions: The reel dimensions are as shown in Figure 3 and Table 3.

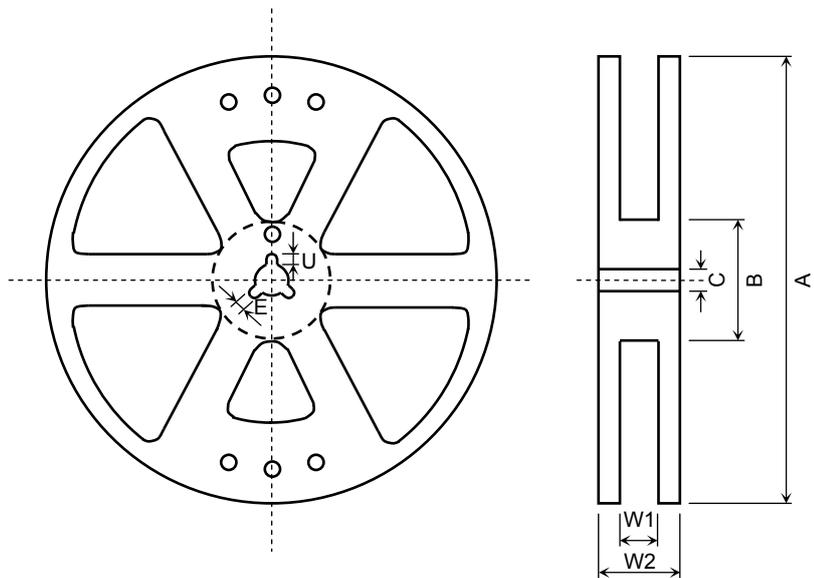


Figure3 Reel Form

Table3 Reel Dimensions

Unit: mm

| Symbol | Dimension |
|--------|-------------------|
| A | $\Phi 330 \pm 2$ |
| B | $\Phi 80 \pm 1$ |
| C | $\Phi 13 \pm 0.5$ |
| E | 2.0 ± 0.5 |
| U | 4.0 ± 0.5 |
| W1 | 13.5 ± 0.5 |
| W2 | 17.5 ± 1.0 |

4. Packing

Either one reel or ten reels of photocoupler are packed in a shipping carton.

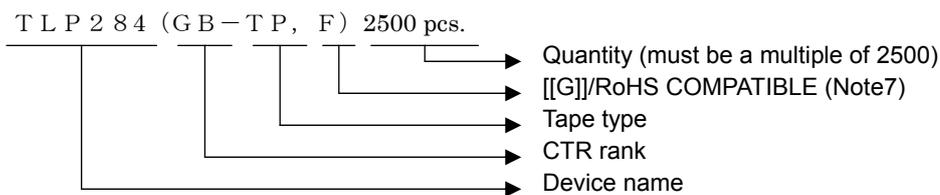
5. Label Indication

The carton bears a label indicating the product number, the symbol representing classification of standard, the quantity, the lot number and the Toshiba company name.

6. Ordering Method

When placing an order, please specify the product number, the CTR rank, the tape type and the quantity as shown in the following example.

(Example)



Note7 : Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.

The RoHS is the Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronics equipment.

Insulation Related Specifications

| | | |
|------------------------------|-----|-------|
| Minimum creepage distance | Cr | 5.0mm |
| Minimum clearance | Cl | 5.0mm |
| Minimum insulation thickness | ti | 0.4mm |
| Comparative tracking index | CTI | 175 |

1. If a printed circuit is incorporated, the creepage distance and clearance may be reduced below this value. (e.g. at a standard distance between soldering eye centers of 3.5mm).
If this is not permissible, the user shall take suitable measures.
2. This photocoupler is suitable for 'safe electrical isolation' only within the safety limit data.
Maintenance of the safety data shall be ensured by means of protective circuit.

VDE test sign : Marking on product
for EN60747



: Marking on packing
for EN60747



Marking Example : TLP284(F)

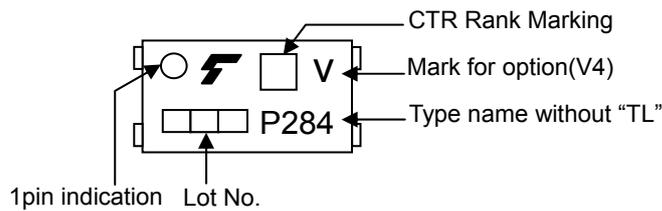


Figure 1 Partial discharge measurement procedure according to EN60747
Destructive test for qualification and sampling tests.

Method A

(for type and sampling tests,
destructive tests)

- t_1, t_2 = 1 to 10 s
- t_3, t_4 = 1 s
- t_p (Measuring time for partial discharge) = 10 s
- t_b = 12 s
- t_{ini} = 60 s

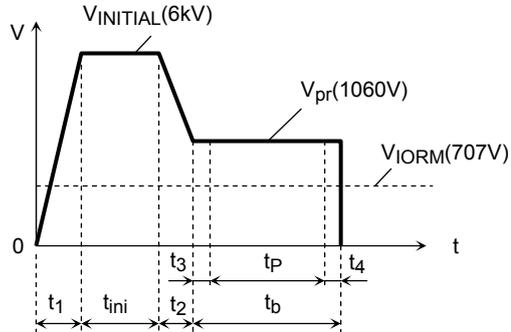


Figure 2 Partial discharge measurement procedure according to EN60747
Non-destructive test for 100% inspection.

Method B

(for sample test, non-destructive test)

- t_3, t_4 = 0.1 s
- t_p (Measuring time for partial discharge) = 1 s
- t_b = 1.2 s

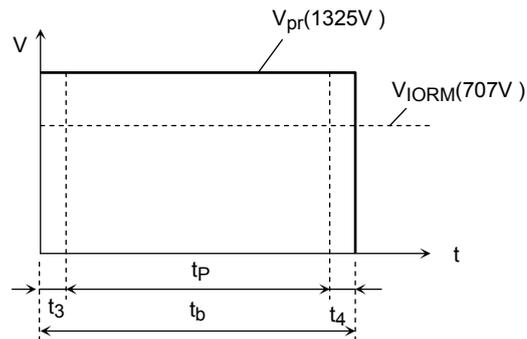
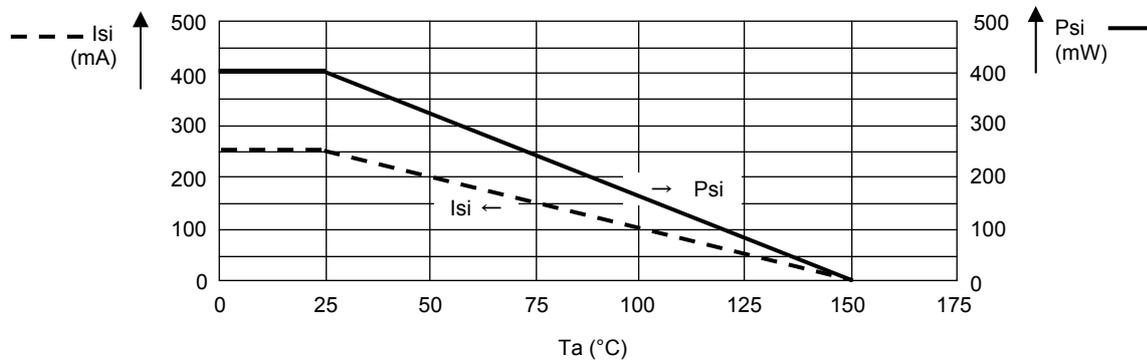


Figure 3 Dependency of maximum safety ratings on ambient temperature



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